

PART INFORMATION

Mfg Item Number	MC10XSC425EK
Mfg Item Name	ESOIC 32 7.5*11*2.3 P.65

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-11-22
Response Document ID	00A0A1.9
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e3
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	MC10XSC425EK
Mfg Item Name	ESOIC 32 7.5*11*2.3 P.65
Version	ALL
Weight	0.482800
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Die Encapsulant	0.3327						g				
Die Encapsulant		Plastics/polymers	4,4'-dihydroxy-3,3',5,5'-tetramethylbiphenyl diglycidyl ether	85954-11-6		0.00514354	g	15460	1.546	10653	1.0653
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00060518	g	1819	0.1819	1253	0.1253
Die Encapsulant		Metals	Magnesium dihydroxide	1309-42-8		0.01193395	g	35670	3.567	24718	2.4718
Die Encapsulant		Solvents, additives, and other materials	Proprietary Material-Other organic phosphorous compounds	-		0.00026383	g	793	0.0793	546	0.0546
Die Encapsulant		Plastics/polymers	1,3,5-Triazine-2,4,6-triamine, polymer with formaldehyde and phenol	25917-04-8		0.00105166	g	3161	0.3161	2178	0.2178
Die Encapsulant		Plastics/polymers	Phenol p-xylylene dimethyl ether copolymer	26834-02-6		0.01209265	g	36347	3.6347	25046	2.5046
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.28406127	g	853806	85.3806	588381	58.8381
Die Encapsulant		Metals	Zinc Hydroxide	20427-58-1		0.00554677	g	16672	1.6672	11488	1.1488
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resins	-		0.01200115	g	36072	3.6072	24857	2.4857
Bonding Wire, Aluminum	0.0127						g				
Bonding Wire, Aluminum		Metals	Aluminum, metal	7429-90-5		0.0127	g	1000000	100	26304	2.6304
Lead Frame Plating	0.0162						g				
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00003224	g	200	0.02	6	0.0006
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.01619676	g	999800	99.98	33547	3.3547
Bonding Wire	0.0014						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0014	g	1000000	100	2899	0.2899
Non-Conductive Epoxy/Adhesive	0.0016						g				
Non-Conductive Epoxy/Adhesive		Metals	Aluminum Oxides (Al2O3)	1344-28-1		0.00107176	g	636000	63.6	2107	0.2107
Non-Conductive Epoxy/Adhesive		Bicides	Boric acid	10043-35-3		0	g	0	0	0	0
Non-Conductive Epoxy/Adhesive		Metals	Boron oxide	1303-86-2		0	g	0	0	0	0
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00004	g	25000	2.5	82	0.0082
Non-Conductive Epoxy/Adhesive		Other Bismaleimides	Other Bismaleimides	-		0.00008096	g	50600	5.06	167	0.0167
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Toluene	108-88-3		0	g	0	0	0	0
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Toluene	147-14-8		0.00000064	g	400	0.04	17	0.0001
Non-Conductive Epoxy/Adhesive		Metals	Copper phthalocyanine	10043-11-5		0.0002208	g	138000	13.8	457	0.0457
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Boron nitride	121-44-8		0	g	0	0	0	0
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Triethylamine	121-44-8		0	g	0	0	0	0
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Isobornyl acrylate	5888-33-5		0.00024	g	150000	15	497	0.0497
Copper Lead Frame	0.1128						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.10873412	g	963955	96.3955	22215	22.2215
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00009306	g	825	0.0825	182	0.0182
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.0028508	g	23500	2.35	5400	0.54
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00001918	g	170	0.017	39	0.0039
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.001128	g	10000	1	2336	0.2336
Copper Lead Frame		Metals	Tin, metal	7440-31-5		0.00003384	g	300	0.03	70	0.007
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.000141	g	1250	0.125	292	0.0292
Epoxy Die Attach	0.0016						g				
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.001216	g	780000	78	2518	0.2518
Epoxy Die Attach		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.0000697	g	43560	4.356	144	0.0144
Epoxy Die Attach		Solvents, additives, and other materials	Poly(methylene polyphenyl isocyanate (PAPI))	9016-87-9		0.0000816	g	5100	0.51	16	0.0016
Epoxy Die Attach		Metals	Dibutyltin disulfate	77-59-7		0.00000054	g	340	0.034	1	0.0001
Epoxy Die Attach		Solvents, additives, and other materials	Alkanes, C14-16	90622-46-1		0.000224	g	140000	14	463	0.0463
Epoxy Die Attach		Plastics/polymers	1,3-Benzenedicarboxylic acid, polymer with 1,4-benzenedicarboxylic acid, 1,4-butanediol and hexanedi	66027-02-9		0.0000816	g	51000	5.1	169	0.0169
Silicon Semiconductor Die	0.0019						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000038	g	20000	2	78	0.0078
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.001862	g	980000	98	3856	0.3856
Silicon Semiconductor Die	0.0019						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000038	g	20000	2	78	0.0078
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.001862	g	980000	98	3856	0.3856

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MC10XSC425EK_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MC10XSC425EK_IPC1752A.xml